L Number	Hits	Search Text	DB	Time stamp
1	681	349/20-22.ccls. 349/161.ccls.	USPAT;	2004/05/04 10:45
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	1	(349/20-22.ccls. 349/161.ccls.) and (dummy adj cell)	USPAT;	2004/05/04 10:45
-	ł	, , , , , ,	US-PGPUB;	
			EPO; JPO;	
			DERWENT:	
	•		IBM_TDB	
3	1008	heat\$3 near10 ((embed\$4 buried burying bury inside) near6	USPAT;	2004/05/04 10:45
		cell)	US-PGPUB;	
			EPO; JPO;	
			DERWENT:	
			IBM_TDB	
4	20	(heat\$3 near10 ((embed\$4 buried burying bury inside) near6	USPAT;	2004/05/04 11:10
		cell)) and 349/\$.ccls.	US-PGPUB;	
	İ	,,	EPO; JPO;	
			DERWENT:	
	1		IBM_TDB	
5	2	"20020089638"	USPAT;	2004/05/04 11:20
			US-PGPUB;	
1			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
6	90	conductive near3 spacer near6 seal\$3	USPAT;	2004/05/04 11:21
		•	US-PGPUB:	
	ļ		EPO; JPO;	
			DERWENT:	
			IBM TDB	
7	146	conduct\$3 near3 spacer near6 seal\$3	USPAT;	2004/05/04 11:21
		<b>.</b>	US-PGPUB;	
			EPO; JPO;	
•			DERWENT;	
			IBM_TDB	
8	67	(conduct\$3 near3 spacer near6 seal\$3) and (heat\$3	USPAT;	2004/05/04 11:22
		(temperature near3 control\$4))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
9	27		USPAT;	2004/05/04 12:13
		(temperature near3 control\$4))) and (display LCD)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
l			IBM_TDB	
10	4	DSTN and heater	USPAT;	2004/05/04 12:13
]			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		20711 10 0 2 1 0	IBM_TDB	0004/05/04 15 15
11	4	DSTN and (heating near3 element)	USPAT;	2004/05/04 12:13
			US-PGPUB;	
			EPO; JPO;	
		·	DERWENT;	
10		DOTN and backer	IBM_TDB	0004/05/04 40 40
12	4	DSTN and heater	USPAT;	2004/05/04 12:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		<u> </u>	IBM_TDB	

13	7	(DSTN and (heating near3 element)) (DSTN and heater)	USPAT;	2004/05/04 12:13
			US-PGPUB;	
į į			EPO; JPO;	
			DERWENT:	
1			IBM TDB	

L Number	Hits	Search Text	DB	Time stamp
1	1	2000JP-0013220.ap,prai.	USPAT;	2004/05/04 14:15
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	934	349/\$.ccls. and ((heating near3 element) heater)	USPAT;	2004/05/04 14:20
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	204	(240/ft calc. and //heating page 2 alamout) heater)) and /	IBM_TDB	2004/05/04 14:20
3	364	(349/\$.ccls. and ((heating near3 element) heater)) and (	USPAT; US-PGPUB:	2004/05/04 14.20
		(plural multiple multi two three several) adj2 (layer panel substrate))	EPO; JPO;	
		Substrate)	DERWENT:	
			IBM TDB	
4	1136	349/\$.ccls. and ( (heating near3 (device element structure))	USPAT:	2004/05/04 14:21
	1100	heater)	US-PGPUB:	
		,,	EPO; JPO;	
			DERWENT,	
			IBM_TDB	
5	690	conduct\$3 near3 spacer same seal\$3	USPAT;	2004/05/04 14:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	7	(349/\$.ccls. and ( (heating near3 (device element structure))	USPAT;	2004/05/04 14:43
		heater)) and (conduct\$3 near3 spacer same seal\$3 )	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	